

BL□

Inductor Type		Series	Size Code in inch (in mm)	Impedance (Ω) at 100MHz							Effective Frequency Range (Applicable Frequency Ranges are only for reference.) 10kHz 100kHz 1MHz 10MHz 100MHz 1GHz 10GHz								
				10	100			1000											
For General Band Noise	Universal Type [Power Lines / Signal Lines]		BLM03AX ^{p15}	0201 (0603)	10	80 120 240			600 1000										
			BLM15AX ^{p25}	0402 (1005)	10	30	70 120 220	600 1000											
	Signal Lines Type	For General Signal Lines	BLM03AG ^{p17}	0201 (0603)	10	80 70 120 240			600 1000										
			BLM15AG ^{p27}	0402 (1005)	10	70 120 220			600 1000										
			BLM18AG ^{p41}	0603 (1608)	220 470 120 150 330 600 1000														
			BLM21AG ^{p51}	0805 (2012)	220 470 120 150 330 600 1000														
		For High Speed Signal Lines	BLM03B ^{p19}	0201 (0603)	10	22	33 56 80 47 75 120	240 470 600 1800											
			BLM15B ^{p29}	0402 (1005)	5 10	22 33 47 75 120	220 470 600 1000												
			BLM18B ^{p44}	0603 (1608)	5 10	22 47 60 75 140 220	420 600 1500 2200												
			BLM21B ^{p53}	0805 (2012)	5	75 200 330 470 750 1500 2200 2700 60 120 150 220 420 600 1000 1800 2250													
	Power Lines Type		BLM03PX* ^{p13}	0201 (0603)	33 (1.5A) 22 (1.8A) 80 (1A)														
			BLM03PG ^{p12}	0201 (0603)	33 (0.75A) 22 (0.9A)														
			BLM15PX* ^{p21}	0402 (1005)	33 (3A) 80 (2.3A) 180 (1.5A) 330 (1.2A) 600 (0.9A) 60 (2.5A) 120 (2A) 220 (1.4A) 470 (1A)														
			BLM15PG/PD* ^{p23}	0402 (1005)	10 (1A)	30 (2.2A) 80 (1.5A) 60 (1.7A) 120 (1.3A)													
			BLM18PG* ^{p35}	0603 (1608)	33 (3A) 120 (2A) 220 (1.4A) 470 (1A) 30 (1A) 60 (0.5A) 180 (1.5A) 330 (1.2A)														
			BLM21PG* ^{p49}	0805 (2012)	30 (4A) 220 (2A) 22 (6A) 60 (3.5A) 120 (3A) 330 (1.5A)														
			BLM31PG* ^{p57}	1206 (3216)	50 (3.5A) 390 (2A) 33 (6A) 120 (3.5A) 600 (1.5A)														
			BLM41PG* ^{p59}	1806 (4516)	75 (3.5A) 470 (2A) 60 (6A) 180 (3.5A) 1000 (1.5A)														
			BLM18KG* ^{p37} (Low DC Resistance Type)	0603 (1608)	30 (5A) 70 (3.5A) 220 (2.2A) 470 (1.5A) 26 (6A) 100 (3A) 120 (3A) 330 (1.7A) 600 (1.3A)														
			BLM18SG* ^{p39} (Low DC Resistance Type)	0603 (1608)	70 (4A) 220 (2.5A) 26 (6A) 120 (3A) 330 (1.5A)														
			BLE32PN ^{p61}	1210 (3225)	30														
For GHz Band Noise	Universal Type [Power Lines / Signal Lines]		BLM03EB* ^{p64}	0201 (0603)	25 (0.6A) 50 (0.4A)														
			BLM15EG* ^{p67}	0402 (1005)	220 (0.7A) 120 (1.5A)														
			BLM18EG* ^{p72}	0603 (1608)	120 (2A) 330 (0.5A) 470 (0.5A) 100 (2A) 220 (2A/1A) 390 (0.5A) 600 (0.5A)														
			BLM18HE* ^{p69}	0603 (1608)	1000 (0.6A) 600 (0.8A) 1500 (0.5A)														
	Signal Lines Type	BLM03HG ^{p62}	0201 (0603)	1000 600 1200															
		BLM03HD ^{p62}	0201 (0603)	600 330 470 1000															
		BLM03HB ^{p62}	0201 (0603)	190															
		BLM15HG ^{p65}	0402 (1005)	600 1000															
		BLM15HD ^{p65}	0402 (1005)	600 1000 1800															
		BLM15HB ^{p65}	0402 (1005)	120 220															
		BLM18HG ^{p69}	0603 (1608)	600 470 1000															
		BLM18HD ^{p69}	0603 (1608)	600 470 1000															
		BLM18HB ^{p69}	0603 (1608)	120 220 330															
For High-GHz Band Noise	Signal Lines Type		BLM15GG ^{p68}	0402 (1005)	220 470														
			BLM15GA ^{p68}	0402 (1005)	75														
			BLM18GG ^{p75}	0603 (1608)	470														

* The derating of rated current is required for some items according to the operating temperature on each product page.

NF□

Capacitor Type	Series	Size Code in inch (in mm)	Capacitance (F)							Effective Frequency Range (Applicable Frequency Ranges are only for reference.)									
			10p	100p	1000p	10000p	0.1μ	1μ	10μ	10kHz	100kHz	1MHz	10MHz	100MHz	1GHz	10GHz			
Universal Type [Power Lines / Signal Lines]	NFM21HC p87	0805 (2012)		22	47	100	220	470	2200		22000	0.1	0.22						
	NFM31HK* p88	1206 (3216)								1000		15000	0.1						
												10000,22000							

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BL Chip Ferrite Bead Part Numbering

(Part Number)

BL	M	18	AG	102	S	Z	1	D
①	②	③	④	⑤	⑥	⑦	⑧	⑨

① Product ID

Product ID	
BL	Chip Ferrite Beads

② Type

Code	Type
E	DC Bias Characteristics Improved Type
M	Ferrite Bead Single Type

③ Dimensions (L×W)

Code	Dimensions (L×W)	EIA
03	0.6×0.3mm	0201
15	1.0×0.5mm	0402
18	1.6×0.8mm	0603
21	2.0×1.25mm	0805
31	3.2×1.6mm	1206
32	3.2×2.5mm	1210
41	4.5×1.6mm	1806

④ Characteristics/Applications

Code ^{*1}	Characteristics/Applications	Series
AG	For General Use	BLM03/15/18/21
AX		BLM03/15
BA	For High-speed Signal Lines	BLM15/18
BB		BLM03/15/18/21
BC		BLM03/15
BD		BLM03/15/18/21
BX		BLM15
PD		BLM15
PG	For Power Lines	BLM03/15/18/21/31/41
PN		BLE32
PX		BLM03/15
KG	For Power Lines (Low DC Resistance Type)	BLM18
SG		
HG	For GHz Band General Use	BLM03/15/18
EB	For GHz Band High-speed Signal Lines (Low Direct Current Type)	BLM03
EG	For GHz Band General Use (Low DC Resistance Type)	BLM15/18
HB	For GHz Band High-speed Signal Lines	BLM03/15/18
HD		BLM03/15/18
HE		BLM18
GA	For High-GHz Band High-speed Signal Lines	BLM15
GG	For High-GHz Band General Use	BLM15/18

*1 Frequency characteristics vary with each code.

⑤ Impedance

Expressed by three figures. The unit is in ohm (Ω) at 100MHz. The first and second figures are significant digits, and the third figure expresses the number of zeros that follow the two figures.

⑥ Electrode

Expressed by a letter.

Ex.)

Code	Electrode
S/T	Sn Plating
A	Au Plating
W	Ag/Pd

⑦ Category

Code	Category	
Z	For Automotive	Infotainment
H		Powertrain, Safety

⑧ Number of Circuits

Code	Number of Circuits
1	1 Circuit

Continued on the following page.

⑨ Packaging

Code	Packaging	Series
K	Embossed Taping (ø330mm Reel)	BLE, BLM21 ^{*1} /31/41
L	Embossed Taping (ø180mm Reel)	
B	Bulk	All Series
J	Paper Taping (ø330mm Reel)	BLM03/15/18/21 ^{*2}
D	Paper Taping (ø180mm Reel)	

^{*1} BLM21BD222S□1/BLM21BD272S□1 only.

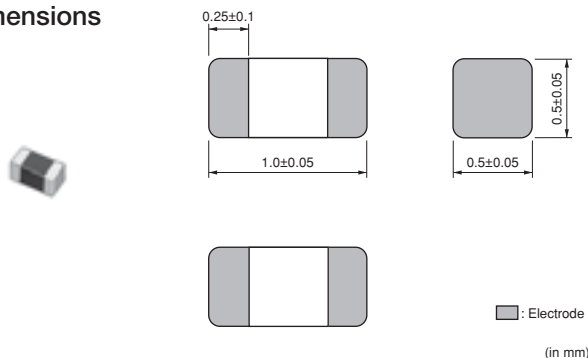
^{*2} Except for BLM21BD222S□1/BLM21BD272S□1

SMD Type
Chip Ferrite BeadSMD Type
Chip EMIFIL®SMD Type
Chip Common Mode Choke CoilSMD Type
Block Type EMIFIL®Lead Type
EMI Suppression FiltersSMD Type
Microchip Transformer (Balun)

BLM15PX Series 0402/1005 (inch/mm)

3A max., high performance type for power lines up to 600ohm.

■ Appearance/Dimensions



■ Packaging

Code	Packaging	Minimum Quantity
D	ø180mm Paper Taping	10000
J	ø330mm Paper Taping	50000
B	Packing in Bulk	1000



■ Equivalent Circuit



(Resistance element becomes dominant at high frequencies.)

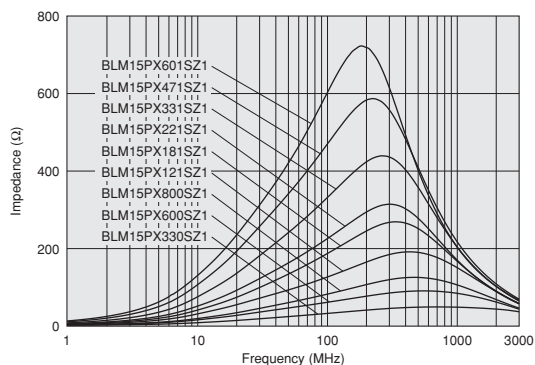
Refer to pages from p.77 to p.80 for mounting information.

■ Rated Value (□: packaging code)

Part Number		Impedance (at 100MHz/20°C)	Rated Current	DC Resistance	Operating Temperature Range
For Infotainment	For Powertrain/Safety				
BLM15PX330SZ1□	—	33Ω ±25%	3000mA	0.022Ω max.	-55°C~+125°C
BLM15PX600SZ1□	—	60Ω ±25%	2500mA	0.032Ω max.	-55°C~+125°C
BLM15PX800SZ1□	—	80Ω ±25%	2300mA	0.038Ω max.	-55°C~+125°C
BLM15PX121SZ1□	—	120Ω ±25%	2000mA	0.055Ω max.	-55°C~+125°C
BLM15PX181SZ1□	—	180Ω ±25%	1500mA	0.090Ω max.	-55°C~+125°C
BLM15PX221SZ1□	—	220Ω ±25%	1400mA	0.10Ω max.	-55°C~+125°C
BLM15PX331SZ1□	—	330Ω ±25%	1200mA	0.15Ω max.	-55°C~+125°C
BLM15PX471SZ1□	—	470Ω ±25%	1000mA	0.20Ω max.	-55°C~+125°C
BLM15PX601SZ1□	—	600Ω ±25%	900mA	0.23Ω max.	-55°C~+125°C

Number of Circuits: 1

■ Impedance-Frequency Characteristics (Main Items)

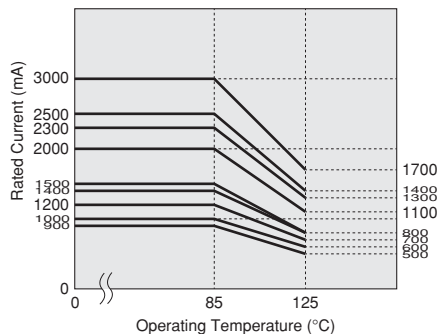


■ Derating of Rated Current

In operating temperature exceeding +85°C, derating of current is necessary for BLM15PX series.

Please apply the derating curve shown in chart according to the operating temperature.

Derating of Rated Current

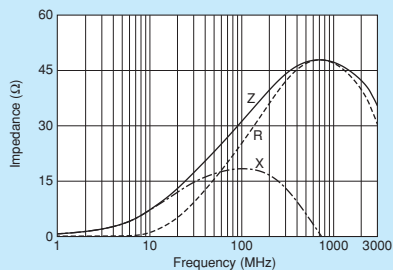


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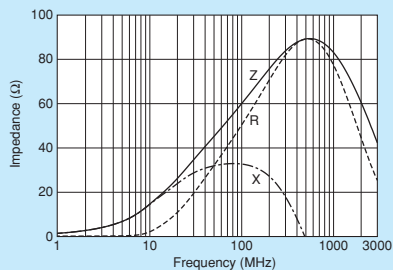
⚠Note • Please read rating and ⚠CAUTION (for storage, operating, rating, soldering, mounting and handling) in this catalog to prevent smoking and/or burning, etc.
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■ Impedance-Frequency Characteristics

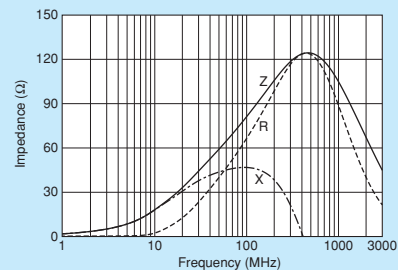
BLM15PX330SZ1



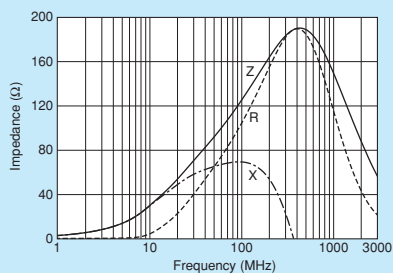
BLM15PX600SZ1



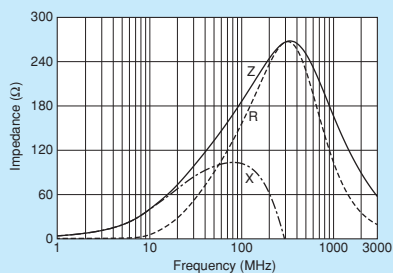
BLM15PX800SZ1



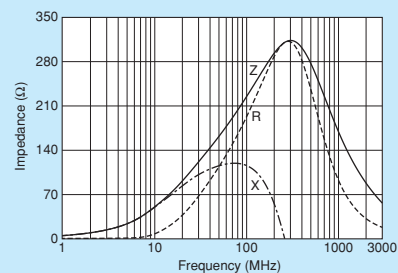
BLM15PX121SZ1



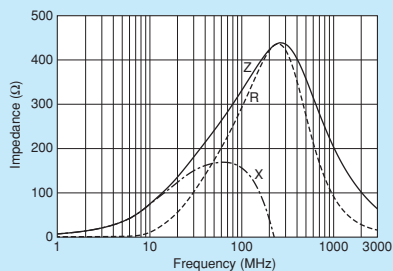
BLM15PX181SZ1



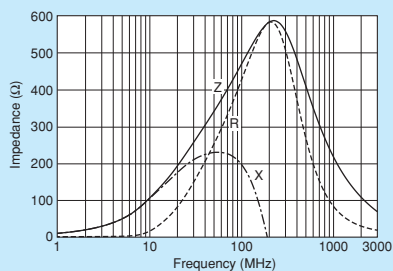
BLM15PX221SZ1



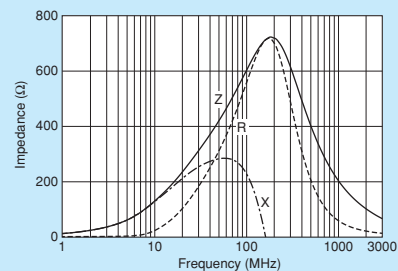
BLM15PX331SZ1



BLM15PX471SZ1



BLM15PX601SZ1



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⚠ Caution

● Rating

1. About the Rated Current
Do not use products beyond the rated current as this may create excessive heat and deteriorate the insulation resistance.
2. About the Excessive Surge Current
Excessive surge current (pulse current or rush current) than specified rated current applied to the product may cause a critical failure, such as an open circuit, burnout caused by excessive temperature rise. Please contact us in advance in case of applying the surge current.

● Soldering and Mounting

- Self-heating
Please pay special attention when mounting chip ferrite beads BLM_AX/P/K/S series bead inductor BLE series in close proximity to other products that radiate heat.
The heat generated by other products may deteriorate the insulation resistance and cause excessive heat in this component.

Notice

● Storage and Operating Conditions

<Operating Environment>

Do not use products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

Do not use products in the environment close to the organic solvent.

<Storage and Handling Requirements>

1. Storage Period
BLM15E/15H/15G series should be used within 12 months, the other series should be used within 6 months.
Solderability should be checked if this period is exceeded.
2. Storage Conditions
 - (1) Storage temperature: -10 to +40°C
Relative humidity: 15 to 85%
Avoid sudden changes in temperature and humidity.
 - (2) Do not store products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

● Notice (Soldering and Mounting)

1. Cleaning
Failure and degradation of a product are caused by the cleaning method. When you clean in conditions that are not in mounting information, please contact Murata engineering.
2. Soldering
Reliability decreases with improper soldering methods. Please solder by the standard soldering conditions shown in mounting information.
3. Mounting on-board with Conductive Glue
BLM18AG_WH is designed for conductive glue mounting method. Please refer to Mounting information.

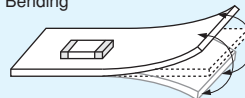
4. Other

Noise suppression levels resulting from Murata's EMI suppression filters EMIFIL® may vary, depending on the circuits and ICs used, type of noise, mounting pattern, mounting location, and other operating conditions. Be sure to check and confirm in advance the noise suppression effect of each filter, in actual circuits, etc. before applying the filter in a commercial-purpose equipment design.

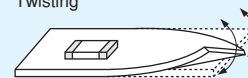
● Handling

1. Resin Coating
Using resin for coating/molding products may affect the products performance.
So please pay careful attention in selecting resin.
Prior to use, please make the reliability evaluation with the product mounted in your application set.
2. Handling of a Substrate
After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.
Excessive mechanical stress may cause cracking in the Product.

Bending



Twisting



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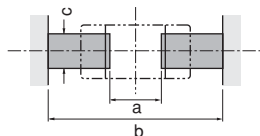
1. Standard Land Pattern Dimensions

Land Pattern + Solder Resist
Land Pattern
Solder Resist

(in mm)

BLE32
BLM03
BLM15
BLM18
BLM21
BLM31
BLM41

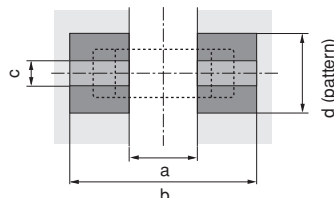
● Reflow and Flow
BLM Series



Type	Soldering	a	b	c
BLM03	Reflow	0.2-0.3	0.6-0.9	0.3
BLM15	Reflow	0.4	1.2-1.4	0.5
BLM18	Flow (except 18G)	0.7	2.2-2.6	0.7
	Reflow		1.8-2.0	
BLM21	Flow/ Reflow	1.2	3.0-4.0	1.0

- Except for BLM03PG-PX-EB/15AX-PD-PG-PX/18PG-KG-SG/21PG. And BLM03/15/18G is specially adapted for reflow soldering.
- BLM18A_WH series is designed for conductive glue mounting method, not for normal soldering method. Please contact us for applicable mounting method for BLM18A_WH series.

BLE32PN·BLM□□AX/P/K/S/E



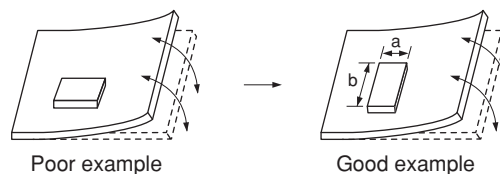
Type	Rated Current (A)	Soldering	a	b	c	Land Pad Thickness and Dimension d		
						18μm	35μm	70μm
BLE32PN	10	Flow/ Reflow	1.9	3.6	2.7	-	4.0 (Temperature 85°C or less)	-
						-	8.0 (Temperature 125°C or less)	-
BLM03AX	0.9max.	Reflow	0.2-0.3	0.6-0.9	0.3	0.3	0.3	0.3
BLM03P□	1.8max.					1.2	0.7	0.3
BLM03EB								
BLM15AX	1.5max.	Reflow	0.4	1.2-1.4	0.5	0.5	0.5	0.5
BLM15PD	2.2max.					1.2	0.7	0.5
BLM15PG	3.0max.					2.4	1.2	0.5
BLM18PG BLM18KG BLM18SG	0.5-1.5	Flow/ Reflow	0.7	Flow 2.2-2.6 Reflow 1.8-2.0	0.7	0.7	0.7	0.7
	1.7-2.5					1.2	0.7	0.7
	3-4					2.4	1.2	0.7
	5-6					6.4	3.3	1.65
BLM21PG	1.5		1.2	3.0-4.0	1.0	1.0	1.0	1.0
	2					1.2	1.0	1.0
	3-4					2.4	1.2	1.0
	6					6.4	3.3	1.65
BLM31PG	1.5-2		2.0	4.2-5.2	1.2	1.2	1.2	1.2
	3.5					2.4	1.2	1.2
	6					6.4	3.3	1.65
BLM41PG	1.5-2		3.0	5.5-6.5		1.2	1.2	1.2
	3.5					2.4	1.2	1.2
	6					6.4	3.3	1.65

- About land pad thickness of BLE32PN, please note the upper limit of the temperature.
- Do not apply narrower pattern than listed above to BLM□□AX/P/K/S. Narrow pattern can cause excessive heat or open circuit.

● PCB Warping

PCB should be designed so that products are not subjected to the mechanical stress caused by warping the board.

Products should be located in the sideways direction (Length: $a < b$) to the mechanical stress.



2. Solder Paste Printing and Adhesive Application

When reflow soldering the chip ferrite beads and bead inductor the printing must be conducted in accordance with the following cream solder printing conditions.

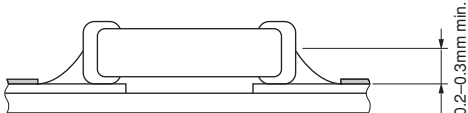
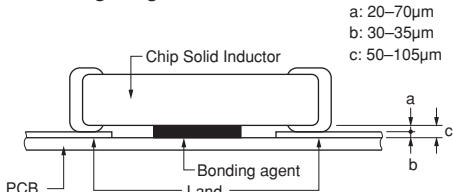
If too much solder is applied, the chip will be prone to damage by mechanical and thermal stress from the PCB and may crack.

Standard land dimensions should be used for resist and copper foil patterns.

When flow soldering the chip ferrite beads and bead inductor apply the adhesive in accordance with the following conditions.

If too much adhesive is applied, then it may overflow into the land or termination areas and yield poor solderability. In contrast, if insufficient adhesive is applied, or if the adhesive is not sufficiently hardened, then the chip may become detached during flow soldering process.

(in mm)

Series	Solder Paste Printing	Adhesive Application
BLM BLE	● Ensure that solder is applied smoothly to a minimum height of 0.2mm to 0.3mm at the end surface of the part. ● Guideline of solder paste thickness: 100-150μm: BLM03 100-200μm: BLM15/18/21/31/41/BLE32 	■ BLM18/21/31/41 Series (Except for BLM18G Series) Coating amount is illustrated in the following diagram. 

3. Standard Soldering Conditions

(1) Soldering Methods

Use flow and reflow soldering methods only.

Use standard soldering conditions when soldering chip ferrite beads and bead inductor.

In cases where several different parts are soldered, each having different soldering conditions, use those conditions requiring the least heat and minimum time.

Solder: Use Sn-3.0Ag-0.5Cu solder. Use of Sn-Zn based solder will deteriorate performance of products. If using BLA series with Sn-Zn based solder, please contact Murata in advance.

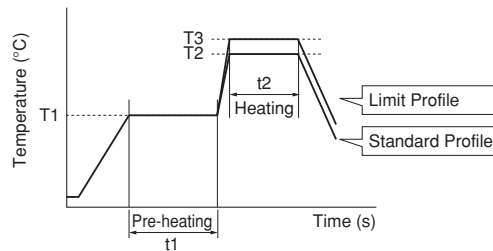
Flux:

- Use Rosin-based flux.
In case of using RA type solder, products should be cleaned completely with no residual flux.
- Do not use strong acidic flux (with chlorine content exceeding 0.20wt%)
- Do not use water-soluble flux.

For additional mounting methods, please contact Murata.

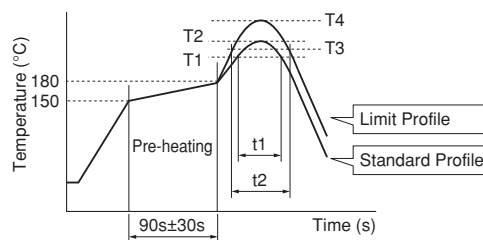
(2) Soldering Profile

● Flow Soldering Profile
(Sn-3.0Ag-0.5Cu Solder)



Series	Pre-heating		Standard Profile			Limit Profile		
			Heating		Cycle of Flow	Heating		Cycle of Flow
	Temp. (T1)	Time. (t1)	Temp. (T2)	Time. (t2)		Temp. (T3)	Time. (t2)	
BLM (Except for BLM03/15/18G/18AG_W) BLE	150°C	60s min.	250°C	4 to 6s	2 times max.	265±3°C	5s max.	2 times max.

● Reflow Soldering Profile
(Sn-3.0Ag-0.5Cu Solder)



Series	Standard Profile				Limit Profile			
	Heating		Peak Temperature (T2)	Cycle of Reflow	Heating		Peak Temperature (T4)	Cycle of Reflow
	Temp. (T1)	Time. (t1)			Temp. (T3)	Time. (t2)		
BLM (Except for BLM18AG_W) BLE	220°C min.	30 to 60s	245±3°C	2 times max.	230°C min.	60s max.	260°C/10s	2 times max.

(3) Reworking with Solder Iron

The following conditions must be strictly followed when using a soldering iron.

Pre-heating: 150°C 60s min.

Soldering iron power output / Tip diameter:

80W max. / ø3mm max.

Temperature of soldering iron tip / Soldering time / Times:
350°C max. / 3-4s / 2 times

Do not allow the tip of the soldering iron to directly contact the chip.

For additional methods of reworking with a soldering iron, please contact Murata engineering.

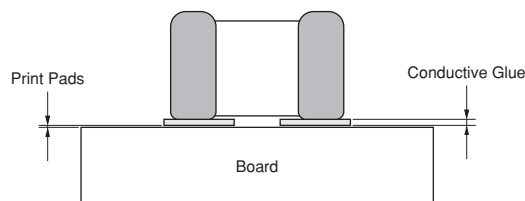
4. Mounting on-board with Conductive Glue of BLM18AG_WH1

Please adhere rigidly to the condition below which shows the method of mounting with conductive glue.

Please coat print pads with conductive glue using metal mask and metal squeegee, and then mount our products on the substrates with a mount machine or human hand.

Please put the substrates into an oven (140 to 150°C) for 30 minutes in order to cure the adhesive.

Please check whether the chips and the substrates are connected with the conductive glue or not and there is no electrical short of the conductive glue.



1. Board	Ceramic Board or Alumina Board
2. Thickness of Glue	30 to 50μm
3. Recommended Conductive Glue	PC3000 (Manufactured by Heraeus)

5. Cleaning

Following conditions should be observed when cleaning chip ferrite beads.

(1) Cleaning Temperature: 60°C max. (40°C max. for alcohol type cleaner)

(2) Ultrasonic

Output: 20W/liter max.

Duration: 5 minutes max.

Frequency: 28 to 40kHz

(3) Cleaning Agent

The following list of cleaning agents have been tested on the individual components. Evaluation of final assembly should be completed prior to production.

Do not clean BLM18AG□□□WH1 series. Before cleaning, please contact Murata engineering.

(a) Alcohol cleaning agent

Isopropyl alcohol (IPA)

(b) Aqueous cleaning agent

Pine Alpha ST-100S

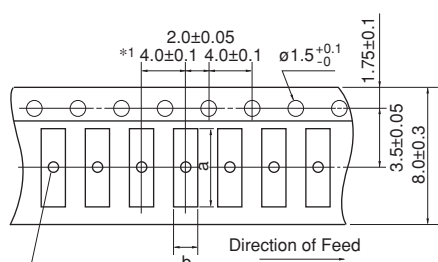
(4) Ensure that flux residue is completely removed.

Component should be thoroughly dried after aqueous agent has been removed with deionized water.

(5) BLM_G type is processed with resin. On rinsing the product, using water for ultrasonic cleaning may affect the resin quality used for the product by water element. In case of set cleaning conditions, please make sure the reliability according to the cleaning conditions.

For additional cleaning methods, please contact Murata engineering.

■ Minimum Quantity and Dimensions of 8mm Width Paper / Embossed Tape

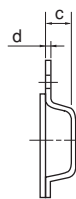


There are holes in the cavities of the BLM21BD222S□1/BD272S□1 and BLM31 only. $\phi 1.0 +0.3 -0$. BLE32 only. $\phi 1.0 +0.2 -0$.

*1 BLM03/15: 2.0 ± 0.05
BLM18S/18T/BLA2A: 2.0 ± 0.1

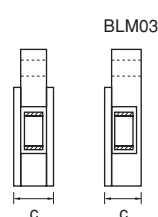
Dimension of the cavity of embossed tape is measured at the bottom side.

<Embossed>



c: Depth of Cavity (Embossed Tape)

<Paper>

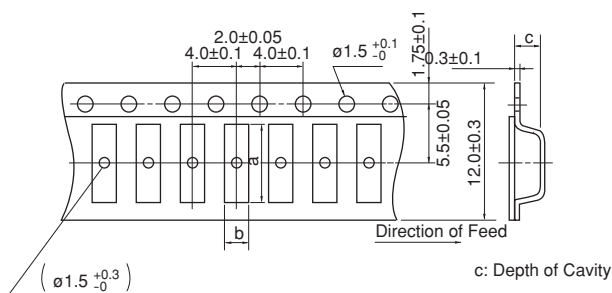


c: Total Thickness of Tape (Paper Tape)

Part Number	Dimensions				Minimum Qty. (pcs.)				
					φ180mm Reel		φ330mm Reel		Bulk
	a	b	c	d	Paper Tape	Embossed Tape	Paper Tape	Embossed Tape	
BLM03	0.70	0.40	0.55 max.	-	15000	-	50000	-	1000
BLM15	1.15	0.65	0.8 max.	-	10000	-	50000	-	1000
BLM18A/B/P/H/G	1.85	1.05	1.1 max.	-	4000	-	10000	-	1000
BLM18EG/KG_T□	1.85	1.05	0.85 max.	-	4000	-	10000	-	1000
BLM18EG/KG_S□			1.1 max.						
BLM18S	1.85	1.05	0.90 max.	-	10000	-	30000	-	1000
BLM21	2.25	1.45	1.1 max.	-	4000	-	10000	-	1000
BLM31	3.5	1.9	1.3	0.2	-	3000	-	10000	1000
BLM21BD222S□1/272S□1	2.25	1.45	1.3	0.2	-	3000	-	10000	1000
BLE32	3.2	2.8	2.3	0.25	-	1500	-	7000	1000

(in mm)

■ Minimum Quantity and Dimensions of 12mm Width Embossed Tape



Dimension of the cavity is measured at the bottom side.

Part Number	Dimensions			Minimum Qty. (pcs.)		
	a	b	c	φ180mm Reel	φ330mm Reel	Bulk
BLM41	4.8	1.9	1.75	2500	8000	1000

(in mm)

"Minimum Quantity" means the number of units of each delivery or order. The quantity should be an integral multiple of the "Minimum Quantity."

⚠Note • Please read rating and ⚠CAUTION (for storage, operating, rating, soldering, mounting and handling) in this catalog to prevent smoking and/or burning, etc.
• This catalog has only typical specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.